

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.14071	100.0	7.3
			Subtotal	0.14071	100	7.3
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.0054	5.0	0.28028
	Pure metal	Silver (Ag)	7440-22-4	0.00162	1.5	0.08409
	Pure metal	Lead (Pb)	7439-92-1	0.10103	93.5	5.24131
			Subtotal	0.10805	100	5.60568
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.17348	100.0	9
			Subtotal	0.17348	100	9
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01914	0.03	0.993
	Copper alloy	Iron (Fe)	7439-89-6	0.0638	0.1	3.31
	Copper alloy	Copper (Cu)	7440-50-8	63.7193	99.87	3305.697
			Subtotal	63.80224	100	3310
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.67465	100.0	35
			Subtotal	0.67465	100	35
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.57954	4.5	81.945
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.51009	10.0	182.1
	Filler	Silica fused	60676-86-0	26.32565	75.0	1365.75
	Metal hydroxide	Metal hydroxide		3.51009	10.0	182.1
	Carbon Black	Carbon black	1333-86-4	0.1755	0.5	9.105
			Subtotal	35.10087	100	1821
			Total	100	100	5187.90568

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